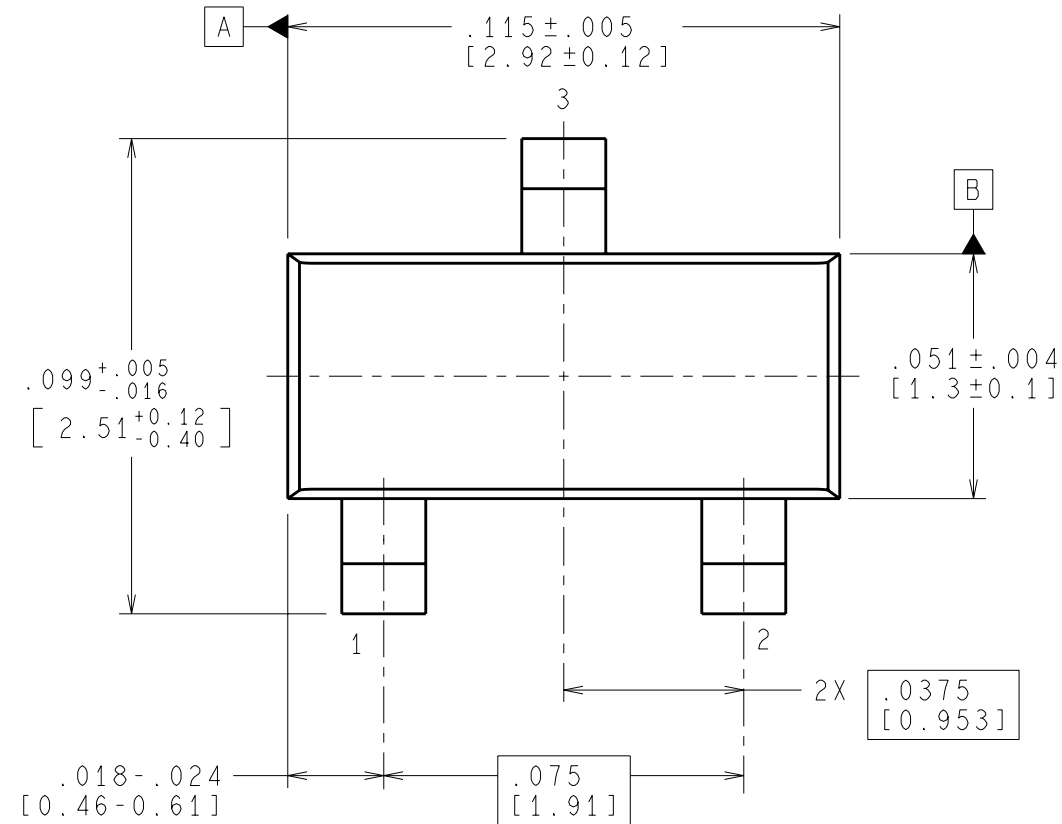
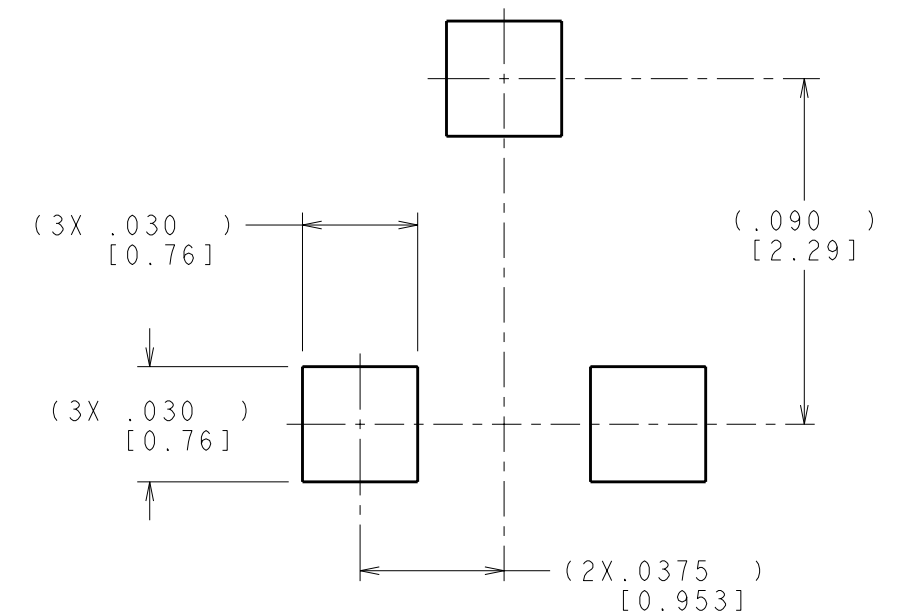


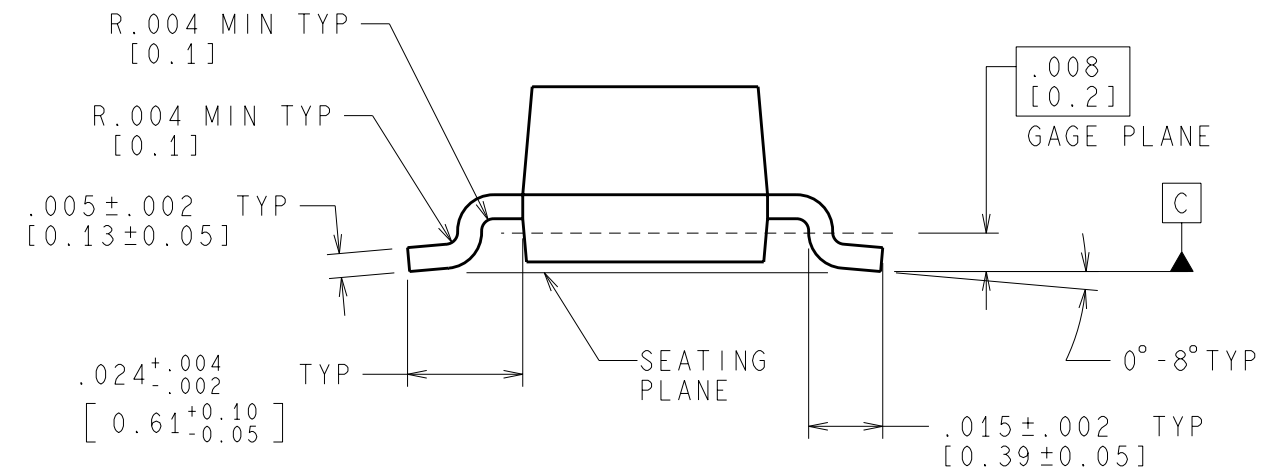
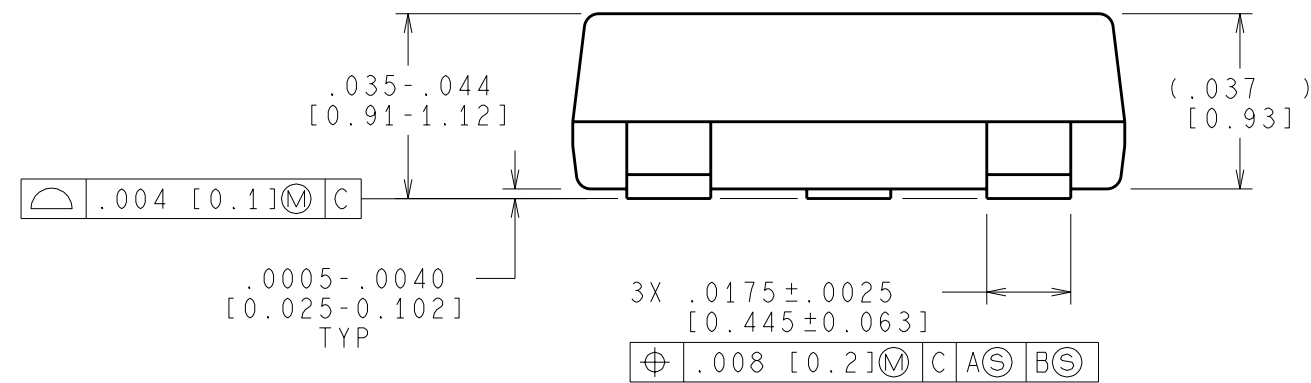
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12340	02/15/2000	TL/RW
B	REVISE NOTE 1; UPDATE NOTE 2; CHANGE DWG FORMAT TO B	983	03/27/2003	TL/RW



CONTROLLING DIMENSION IS INCH  
VALUES IN [ ] ARE MILLIMETERS



RECOMENDED LAND PATTERN



NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE ([www.national.com](http://www.national.com)).
- REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB.

APPROVALS	DATE	National Semiconductor	
DRAWN T. LEQUANG	02/15/2000	2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DTG. CHK. MARTA SUCHY	03/27/2003	MOLDED SOT-23, .115x.051x.037 in BODY, 3 LD, .075 in PITCH	
ENGR. CHK. RANDY WALBERG	03/27/2003		
PROJECTION	SCALE	SIZE	DRAWING NUMBER
	NTS	B	(SC)MKT-MF03A
FORMERLY: N/A	SHEET 1 of 1		REV B